



DUAL N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(ON)} Max	I _D Max T _A = +25°C (Note 5)
40V	$31m\Omega$ @ $V_{GS} = 10V$	7.0A
	$50m\Omega @ V_{GS} = 4.5V$	5.6A

Features and Benefits

- Low On-Resistance
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- · Qualified to AEC-Q101 Standards for High Reliability
- An Automotive-Compliant Part is Available Under Separate Datasheet (<u>DMN4031SSDQ</u>)

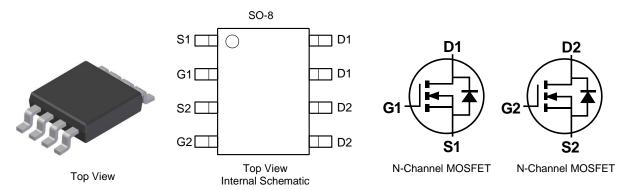
Description and Applications

This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}), yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Motor Control
- Backlighting
- Power Management Functions
- DC-DC Converters

Mechanical Data

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 (§3)
- Weight: 0.072 grams (Approximate)



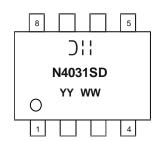
Ordering Information (Note 4)

Part Number	Case	Packaging
DMN4031SSD-13	SO-8	2,500/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



⊃¦¦ = Manufacturer's Marking
 N4031SD = Product Type Marking Code
 YYWW = Date Code Marking
 YY or YY = Year (ex: 16 = 2016)
 WW = Week (01 - 53)



Characteristic	Symbol	Value	Units		
Drain-Source Voltage			V _{DSS}	40	V
Gate-Source Voltage			V_{GSS}	±20	V
Continuous Drain Current (Note 5) (V _{GS} = 10V)	Steady State	$T_A = +25$ °C $T_A = +70$ °C	I _D	5.2 4.1	А
Continuous Drain Current (Note 5) (V _{GS} = 4.5V)	Steady State	$T_A = +25$ °C $T_A = +70$ °C	I _D	4.3 3.4	А
Continuous Drain Current (Note 6) (V _{GS} = 10V)	Steady State	$T_A = +25$ °C $T_A = +70$ °C	I _D	7.0 5.6	А
Continuous Drain Current (Note 6) (V _{GS} = 4.5V)	Steady State	$T_A = +25$ °C $T_A = +70$ °C	I _D	5.8 4.7	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%	I _{DM}	40	Α		
Maximum Continuous Body Diode Forward Current	Is	2.2	Α		
Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle = 1%)			I _{SM}	40	А
Avalanche Current, L = 0.1mH (Note 7)	I _{AS}	11	А		
Avalanche Energy, L = 0.1mH (Note 7)			Eas	18	mJ

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 5)	P_{D}	1.42	W
Thermal Resistance, Junction to Ambient @T _A = +25°C (Note 5)	$R_{ heta JA}$	88	°C/W
Total Power Dissipation (Note 6)	P_{D}	2.6	W
Thermal Resistance, Junction to Ambient @T _A = +25°C (Note 6)	$R_{\theta JA}$	48	°C/W
Operating and Storage Temperature Range	$T_{J,}T_{STG}$	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
DFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV _{DSS}	40	l		٧	$V_{GS} = 0V$, $I_D = 10mA$	
Zero Gate Voltage Drain Current	I _{DSS}		-	1	μΑ	$V_{DS} = 40V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V _{GS(TH)}	1.6	2.4	3.0	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
On-state drain current	I _{D(ON)}	20	_	_	Α	$V_{GS} = 10V, V_{DS} = 5A$	
Static Drain-Source On-Resistance	-	_	19	31	mΩ	$V_{GS} = 10V, I_D = 6A$	
Static Drain-Source On-Resistance	R _{DS(ON)}	_	44	50		$V_{GS} = 4.5V, I_D = 5A$	
Forward Transfer Admittance	Y _{FS}	_	11	_	S	$V_{DS} = 5V, I_{D} = 6A$	
Diode Forward Voltage	V _{SD}	_	0.74	1.0	V	$V_{GS} = 0V, I_{S} = 1A$	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	C _{ISS}		945	-	pF	.,	
Output Capacitance	Coss	1	69		pF	$V_{DS} = 20V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance	C _{RSS}	_	58	_	pF	T = 1.UIVIMZ	
Gate resistance	R_{G}	_	1.45	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Q_{G}	_	8.4	_	nC		
Total Gate Charge (V _{GS} = 10V)	Q_{G}	_	18.6		nC	$V_{GS} = 10V, V_{DS} = 20V,$ $I_{D} = 12A$	
Gate-Source Charge	Q _{GS}	_	3.3	_	nC		
Gate-Drain Charge	Q_{GD}	_	2.2		nC]	
Turn-On Delay Time	T _{D(ON)}		6.4		ns		
Turn-On Rise Time	T _R		9.7		ns	$V_{GS} = 10V, V_{DS} = 20V,$	
Turn-Off Delay Time	T _{D(OFF)}		19.8		ns	$R_L=1.6\Omega, R_G=3\Omega$	
Turn-Off Fall Time	T _F		3.1		ns		

5. Device mounted on FR-4 PCB, with minimum recommended pad layout. The value in any given application depends on user's specific board design Notes:

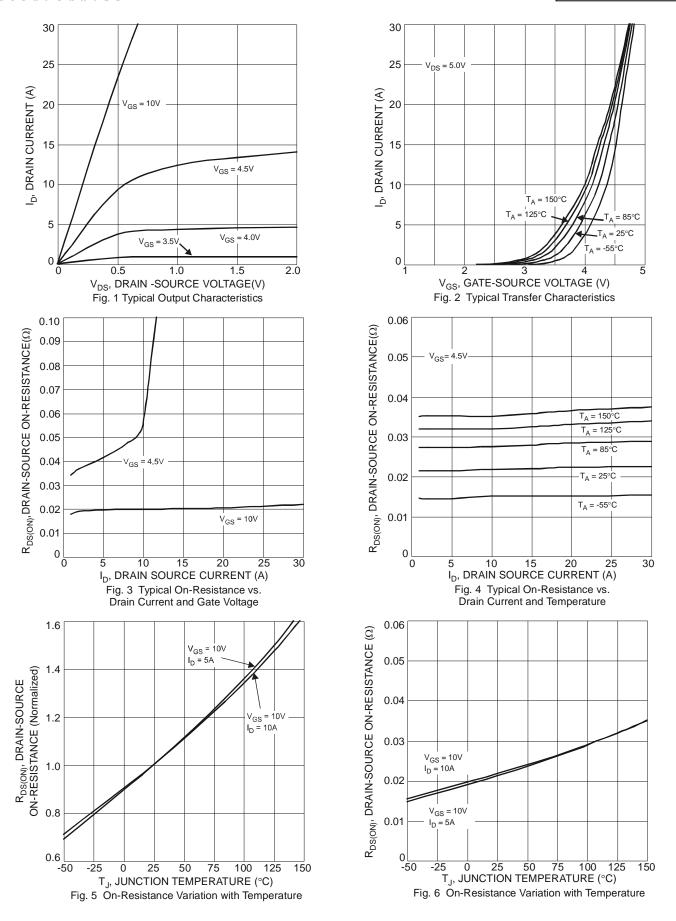
^{6.} Device mounted on 1" x 1" FR-4PCB with high coverage 1 oz. copper, single sided.

^{7.} IAS and EAS rating are based on low frequency and duty cycles to keep $T_J = +25$ °C.

^{8.} Short duration pulse test used to minimize self-heating effect.

^{9.} Guaranteed by design. Not subject to product testing.







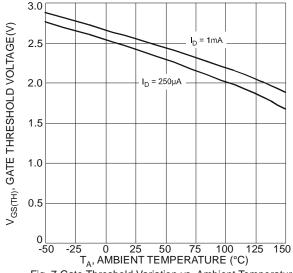
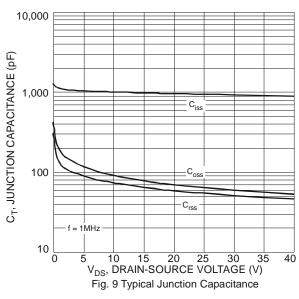
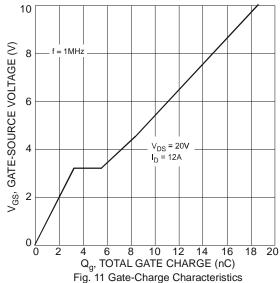
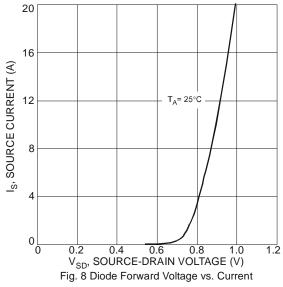


Fig. 7 Gate Threshold Variation vs. Ambient Temperature







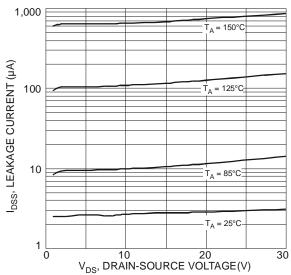
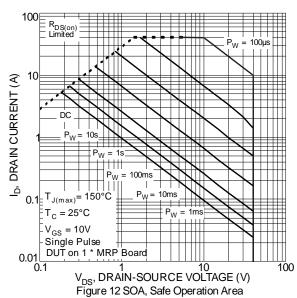
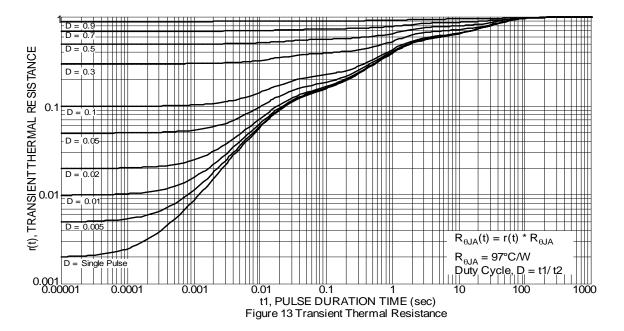


Fig. 10 Typical Drain-Source Leakage Current vs. Voltage





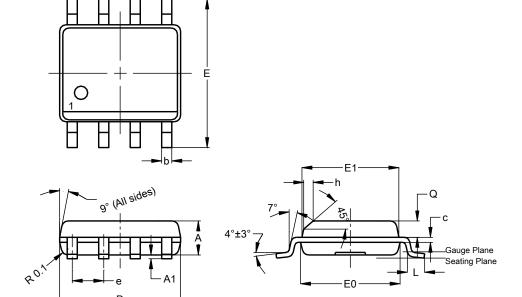




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

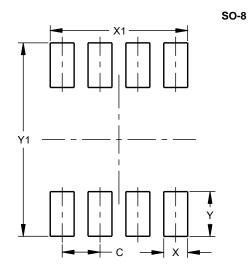
SO-8



SO-8					
Dim	Min	Max	Тур		
Α	1.40	1.50	1.45		
A1	0.10	0.20	0.15		
p	0.30	0.50	0.40		
С	0.15	0.25	0.20		
D	4.85	4.95	4.90		
Е	5.90	6.10	6.00		
E1	3.80	3.90	3.85		
E0	3.85	3.95	3.90		
е	_	_	1.27		
h	_	_	0.35		
Г	0.62	0.82	0.72		
Ø	0.60	0.70	0.65		
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
С	1.27
Х	0.802
X1	4.612
Y	1.505
Y1	6.50



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